

## ISPD 2025 Closing Remarks

Stephan Held (University of Bonn)

Technical program chair for ISPD 2025 and general chair for ISPD 2026

#### Outline



- ISPD 2025 registration demographics
- ACM TODAES special issue
- Paper submission demographics
- Best paper award
- Outlook to ISPD 2026

 Join us afterwards for a Texas barbeque & Austin city tour

### Registration Demographics



- We have 95 people registered for ISPD 2025:
  - 28.5% academia, including students (17.9% of total attendees),
    71.5% industry
  - 27.4 are IEEE members and 22.1 % are ACM members
- We have representatives from eight countries:
  - USA 82%, Taiwan 4%, Republic of Korea 3%, Hong Kong 3 %, Germany 2%, China 2%, US Minor Outlying Islands 2%, Singapore 1%
- Thank you so much for attending ISPD 2025!
- A big thank you to all of you, the speakers, sessions chairs, committee members, reviewers, ACM and our sponsors for making this such a great conference.

#### Physical Design Journal Issue



- The TODAES special issue on Advances in Physical Design for ACM Transactions on Design Automation of Electronic Systems will appear this summer 2025 (facing some delays)
- Next planned special issue:
  Paper submission in the summer of 2026

## ISPD Submission • Demographics

- 64 abstract submissions (+2)
- 48 papers reviewed (same as last year),223 reviews
- 18 papers accepted (37.5%)

Location Demographics for Submitted Paper Authors	Percentage
United States	39.2
China	23.7
Taiwan	13.9
Hong Kong	8.8
Germany	4.1
India	4.1
Brazil	2.6
Canada	1.0
United Kingdom	1.0
Costa Rica	0.5
Greece	0.5
Thailand	0.5

## 

Session Acceleration:

Cypress: VLSI-Inspired PCB Placement with GPU Acceleration

Niansong Zhang, Anthony Agnesina, Noor Shbat, Yuval Leader, Zhiru Zhang and Haoxing Ren (Cornell University, NVIDIA)

Session AI for Chip Design:

HeLO: A Heterogeneous Logic Optimization Framework by Hierarchical Clustering and Graph Learning

Yuan Pu, Fangzhou Liu, Zhuolun He, Keren Zhu, Rongliang Fu, Ziyi Wang, Tsung-Yi Ho and Bei Yu (The Chinese University of Hong Kong, Fudan University)

Session LLM for Chip Design:

LEGO-Size: LLM-Enhanced GPU-Optimized Signoff-Accurate Differentiable VLSI Gate Sizing in Advanced Nodes

Yi-Chen Lu, Kishor Kunal, Geraldo Pradipta, Rongjian Liang, Ravikishore Gandikota, and Haoxing Ren (NVIDIA)



## Cypress: VLSI-Inspired PCB Placement with GPU Acceleration

Niansong Zhang, Anthony Agnesina, Noor Shbat, Yuval Leader, Zhiru Zhang and Haoxing Ren (Cornell University, NVIDIA)

Congratulations!

## International Symposium on Physical Design



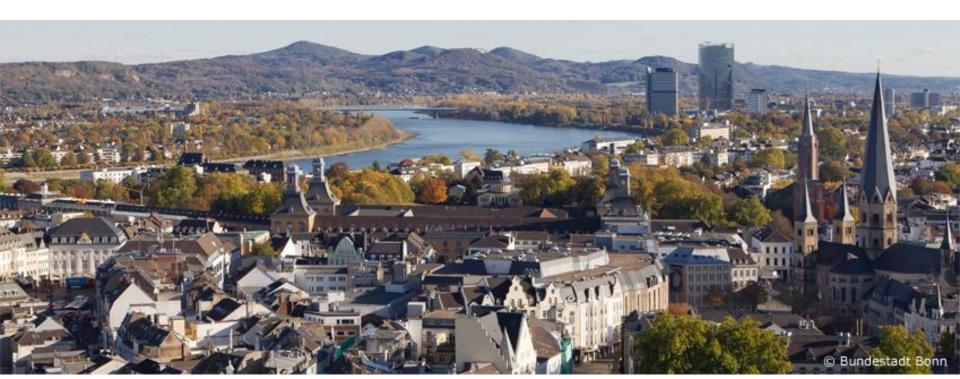
March 2026 Bonn, Germany



#### Outlook to ISPD 2026

#### Bonn, Germany

March 2026



# City of Beethoven, Mathematics, DHL, Haribo & Design Automation









# We are looking forward to seeing you all in Bonn!

